RELPACK 2017

IMAPS-UK Conference

Reliability Engineering for Electronic Packaging

30th November 2017, STFC – Daresbury Laboratory

Highlights:

Why Reliability is Important
Multi-Physics Modelling
Significance of Hermeticity
Design for Reliability
Highly Accelerated Life Testing
Lifetime Predictions
Failure Analysis Methods
Excellent Networking Opportunities
Access Reliability Service Providers

The reliability of electronics is almost taken for granted, with a few notable exceptions, which hit the headlines around the world. Behind the scenes, extensive work is carried out to prove the reliability of electronic components/modules and demonstrate their fitness for purpose from consumer products through to safety critical applications in medical, automotive and aerospace.
Packaging and assembly processes are key elements governing both the manufacturing reliability and longevity of electronic products, but the science and engineering in determining reliability are often overlooked in satisfying minimum qualification requirements.

This conference aims to bring together an array of electronics packaging experts and reliability service providers to present a comprehensive review of the spectrum of reliability engineering, including modelling to predict lifetimes, materials design for reliability, importance of hermeticity, failure analysis methods, highly accelerated life testing and reliability testing for power modules, solar cells and wearables.

Join us at the prestigious one day event to learn, network and source in the field of reliability engineering for electronics packaging.

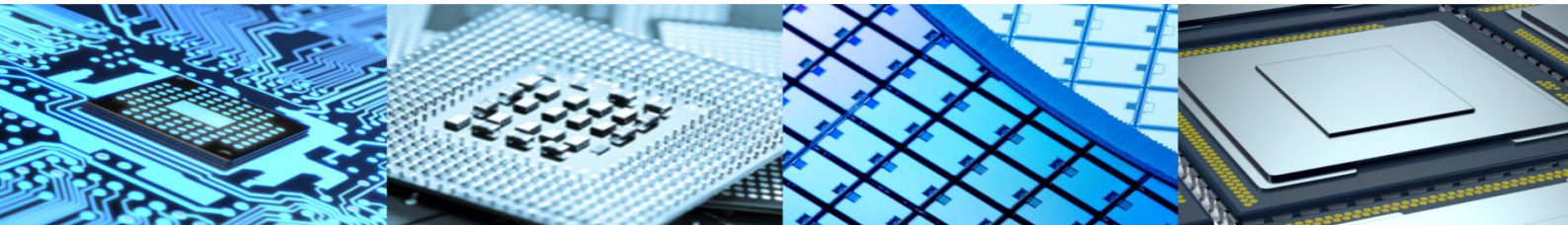
Registration:

http://www.imaps.org.uk

	Delegates	*Exhibitors*
Student	***45***	***NA***
IMAPS member	***75***	***350***
Non member	***125***	***500***

Prices - £ exclude VAT, inclusive of parking, lunch & refreshments

"Where the Industry Meets"



Conference Agenda:

- Registration, Exhibition, Networking & Exhibitor Briefings

Opening Keynote:

- What is reliability testing in today's competitive low cost materials: Martin Shaw, Reliability Solutions

Session One: Design, Modelling & Measurement

- Materials design for inherent harsh environment reliability: Colin Johnston, Oxford University
- Modelling for reliability and lifetime prediction: Chris Bailey, University of Greenwich
- The use of thermal warpage metrology methods in electronic reliability testing: Neil Hubble, Akrometrix

Session Two: Reliability Testing/Failure Analysis

- Thermal and electrical degradation in power electronic modules: Mark Johnson, Nottingham University
- Use of design of experiments for qualitative accelerated life testing of next-generation solar cells: Jeff Kettle, University of Bangor
- Reliability testing of wearables: Martin Wickham/Adam Lewis, NPL
- Failure analysis methods and case studies: Stewart McCracken, MCS

Session 3: Significance of Hermeticity

- Hermeticity tests and lifetime predictions for medical devices: Anne Vanhoest, UCL
- Hermetic glass packaging for demanding applications: Ville Hevonkorpi, Primoceler

Conference Venue:

Daresbury Laboratory, SciTech Daresbury
Keckwick Lane, Daresbury
Warrington WA4 4AD

Exhibitor Opportunities:

Interested in attending RELPACK 2017 as an exhibitor? A limited number of table-tops are available on a first-come, first-served basis; book early to avoid disappointment.
All exhibitors receive listings on the IMAPS-UK website, entries in the event programme, plus the opportunity to provide a short presentation to the delegates during the opening briefing at the start of the Seminar.

Exhibitor Rates:
IMAPS Corporate Member: £350
Non Member: £500

Sponsorship Opportunities:

Please contact us if you or your Company is interested in raising its profile even further at RELPACK 2017 via our Sponsorship opportunities. In addition to recognition of our sponsors at the start of the Conference, the following packages & benefits are available:

- Premier Event Sponsors: Free exhibitor table-top, two delegate places, free advert in the event handbook with promotional leaflets distributed to all delegates, logo on all promotional material and online with weblink.
- Handbook sponsors, two free full page adverts, one either inside front or back and another unspecified & one free delegate space

Please contact the IMAPS Secretariat for further details.